# ne<mark>x</mark>peria

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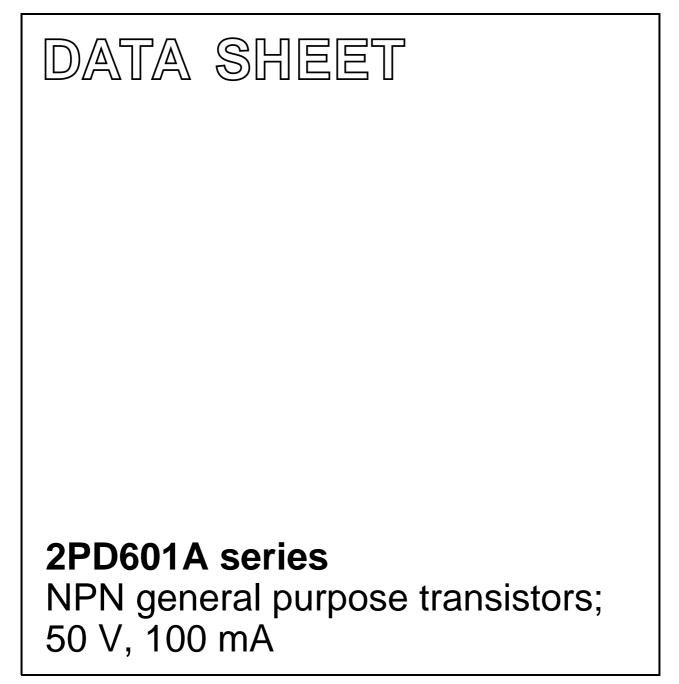
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2002 Jun 26 2004 Feb 12



### 2PD601A series

#### FEATURES

- Available in SOT323 (SC-70) and SOT346 (SC-59) packages
- Available in three different DC current gain versions (Q, R, S).

#### APPLICATIONS

• General purpose switching and amplification.

#### DESCRIPTION

NPN general purpose transistors (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	– 50 V		V
I <sub>C</sub>	collector current (DC)	-	100	mA
h <sub>FE</sub>	DC current gain			
	group Q	160	260	
	group R	210	340	
	group S	290	460	

TYPE NUMBER	PACKAGE		MARKING CODE		
PHILIPS EIAJ			h <sub>FE</sub> GROUP		
2PD601AQ	SOT346	SC-59	ZQ	Q	
2PD601AR	SOT346	SC-59	ZR	R	
2PD601AS	SOT346	SC-59	ZS	S	
2PD601AQW	SOT323	SC-70	*6D	Q	
2PD601ARW	SOT323	SC-70	*6E	R	
2PD601ASW	SOT323	SC-70	*6F	S	

#### Note

1. \* = p: Made in Hong Kong.

\* = t: Made in Malaysia.

\* = W: Made in China.

#### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL		PINNING	
ITPE NUMBER			DESCRIPTION	
2PD601AQ		1	base	
2PD601AR		2	emitter	
2PD601AS	3	3	collector	
2PD601AQW				
2PD601ARW				
2PD601ASW				
	Top view MAM321			

#### Product data sheet

### 2PD601A series

#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE			
ITPE NUMBER	NAME	DESCRIPTION	VERSION	
2PD601AQ	_	plastic surface mounted package; 3 leads	SOT346	
2PD601AR				
2PD601AS				
2PD601AQW	_	plastic surface mounted package; 3 leads	SOT323	
2PD601ARW				
2PD601ASW				

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	—	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	6	V
I <sub>C</sub>	collector current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		—	200	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1			
	SOT346		-	250	mW
	SOT323		-	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Refer to SOT346 (SC-59) and SOT323 (SC-70) standard mounting conditions.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1		
	SOT346		500	K/W
	SOT323		625	K/W

#### Note

1. Refer to SOT346 (SC-59) and SOT323 (SC-70) standard mounting conditions.

#### Soldering

Reflow soldering is the only recommended soldering method.

### 2PD601A series

#### CHARACTERISTICS

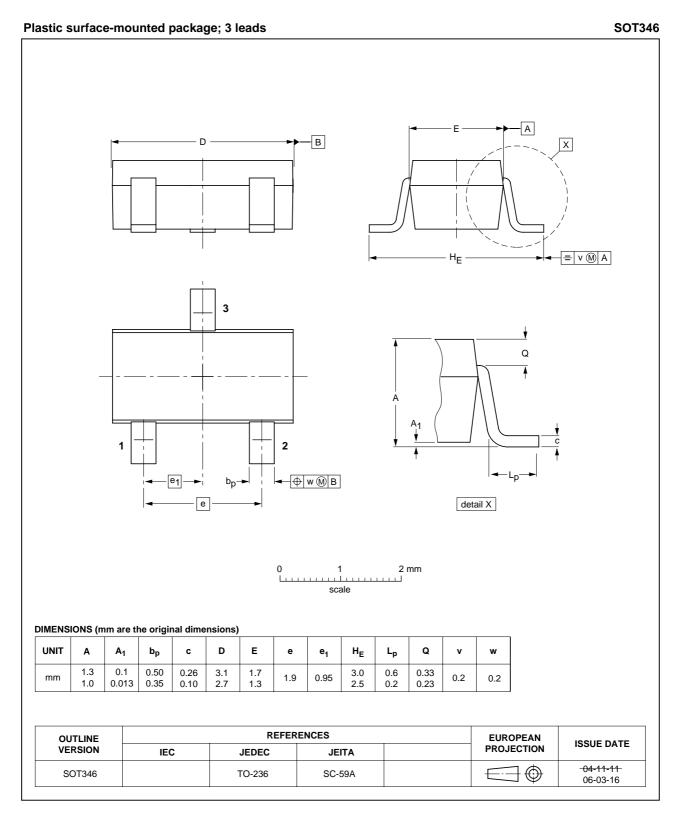
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 60 V	_	10	nA
		$I_E = 0; V_{CB} = 60 V; T_j = 150 °C$	-	5	μA
I <sub>EBO</sub>	emitter-base cut-off current	$I_{C} = 0; V_{EB} = 5 V$	-	10	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 2 V; note 1	90	-	
h <sub>FE</sub>	DC current gain	$I_{C} = 2 \text{ mA}; V_{CE} = 10 \text{ V}$			
	group Q		160	260	
	group R		210	340	
	group S		290	460	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 10 mA; note 1	-	250	mV
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V; f = 1 MHz$	-	3	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 2 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	100	-	MHz

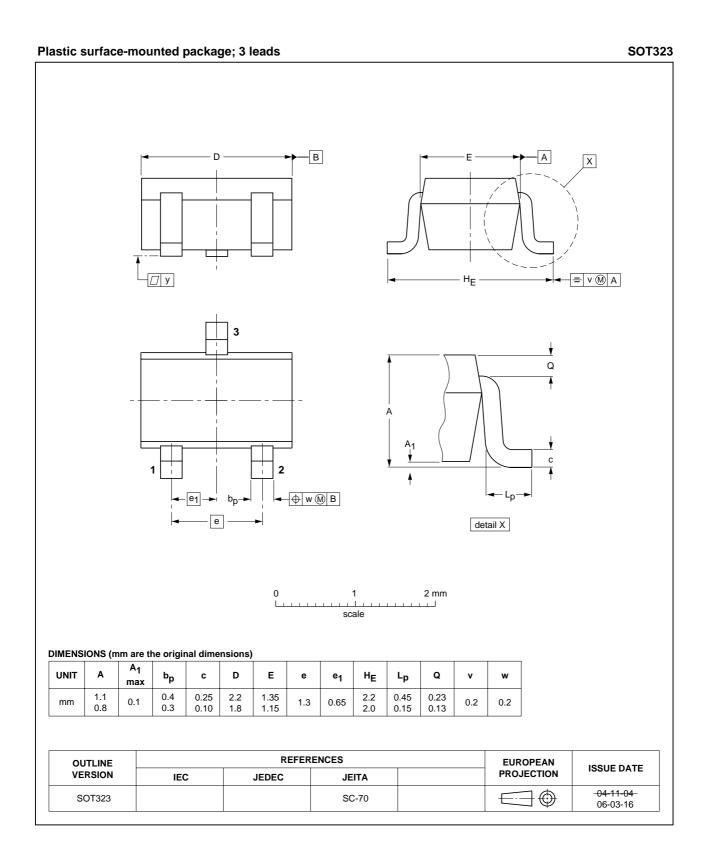
#### Note

1. Pulse test:  $t_p \leq 300~\mu s;~\delta \leq 0.02.$ 

#### PACKAGE OUTLINES



### 2PD601A series



### 2PD601A series

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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### **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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